

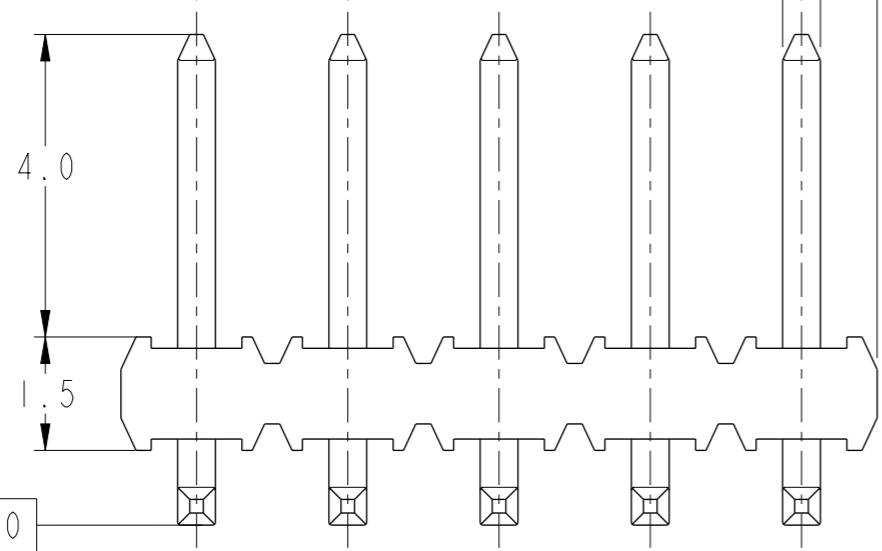
2.00 ± 0.25 TYP
NON-ACCUM

2.0 ± 0.13 ON TIP
± 0.1 ON BASE TYP

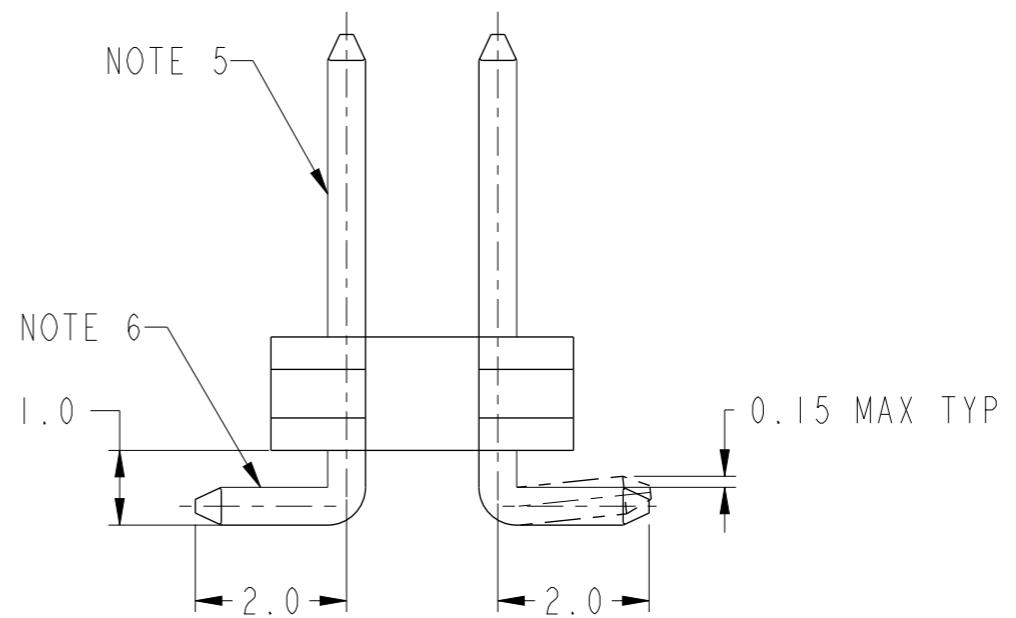
DIM X ± 0.2 ON TIP
± 0.13 ON BASE

NOTE 3

0.50 ± 0.02 SQ PIN



0.10
NOTE 8



Amphenol
FCi

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spec ref		dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	10:1
tolerance std		eng	Laurence Zang	2017/07/06			ecn no		ELX-N-27403-1	
ISO 406 ISO 1101		chr	-	-			rel level		Released	
TOLERANCES UNLESS OTHERWISE SPECIFIED		appr	Tim Yao	2017/07/06	product family		MINITEK		rev	
surface	linear	0.X		± 0.3	Amphenol FCI MINITEK 2.0 SMT STR HEADER		dwg no 94262		rev E	
		0.XX		± 0.25						
0.XXX		± 0.10								
ISO 1302		angular	0°		± 3°		cat. no.		-	
Product - Customer Drw							sheet 1 of 3			

PRODUCT NO.	POS	DIM X	DIM Y
94262-X04	2X2	2	4
X06	2X3	4	6
X08	2X4	6	8
X10	2X5	8	10
X12	2X6	10	12
X14	2X7	12	14
X16	2X8	14	16
X18	2X9	16	18
X20	2X10	18	20
X22	2X11	20	22
X24	2X12	22	24
X26	2X13	24	26
X28	2X14	26	28
X30	2X15	28	30
X32	2X16	30	32
X34	2X17	32	34
X36	2X18	34	36
X38	2X19	36	38
X40	2X20	38	40
X42	2X21	40	42
X44	2X22	42	44
X46	2X23	44	46
X48	2X24	46	48
X50	2X25	48	50

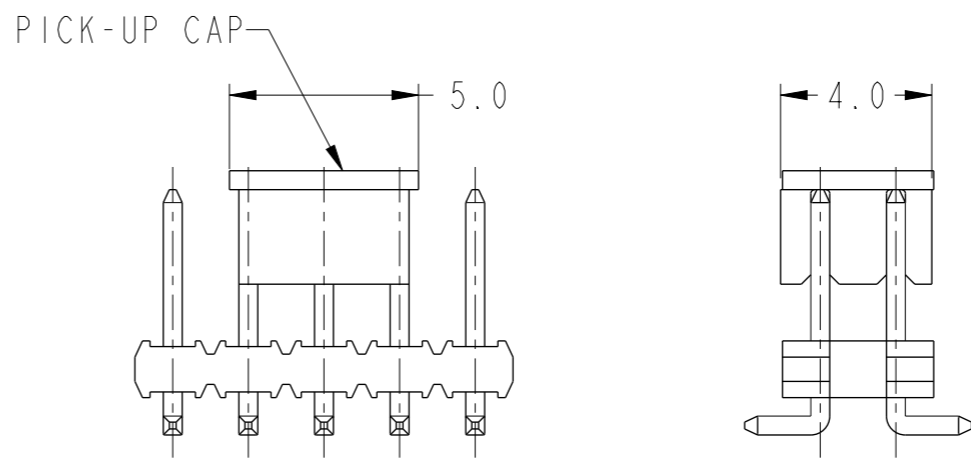
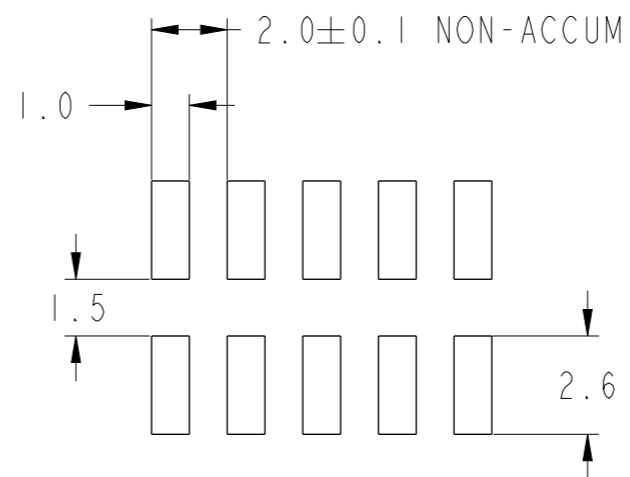


FIG. 1
NOTE 7 (c)
SCALE 5:1



RECOMMENDED PAD LAYOUT

dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	5:1	
eng	Laurence Zang	2017/07/06			ecn no	ELX-N-27403-1			
chr	-	-			product family	MINITEK	rel level	Released	
appr	Tim Yao	2017/07/06						rev	E
cat. no.		-	Product - Customer Drw			sheet 2 of 3			

NOTES:

1. MATERIAL:
BODY : HIGH TEMPERATURE PLASTIC UL 94V-0 BLACK
PIN : COPPER ALLOY
2. TOLERANCE UNLESS OTHERWISE NOTED ± 0.25
- ③ DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY.
IF SIDE(S) ARE BROKEN, DIM 1.5 MAX APPLIES.
- ④ RECESS APPLIES TO MOLDED SIDE(S) ONLY.
- ⑤ PLATING ON MATING LENGTH:
-3XXLF --- 0.38 μ m Au OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-5XXLF --- 0.38 μ m PdNi W Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
-6XXLF --- 0.76 μ m PdNi W Au FLASH OVER 1.27 μ m MIN NICKEL UNDERPLATE.
- ⑥ SOLDER TAIL PLATING:
SOLDERTAIL OF P/N:94262-XXXLF IS PLATED WITH 3.81 μ m MIN 100%
MATTE TIN PLATING OVER 1.27 μ m MIN Ni UNDERPLATE.
7. PACKAGING:
a) STANDARD PACKAGING IN PE BAG.
b) SPECIFY 94262-XXXTLF FOR TUBE PACKAGING.
c) SPECIFY 94262-XXXTRLF FOR TAP AND REEL PACKAGING.
A PICK-UP CAP IS PROVIDED IN THE CENTRE OF
THE PRODUCT (SEE FIG.1) FOR PICK AND PLACE APPLICATION.
8. COPLANARITY OF SOLDER LEADS TO BE WITHIN 0.10mm.
- ⑨ PRODUCT DESCRIPTION CODE:
XXXXX-XXXLF

LEAD FREE. SEE NOTES 6 & 12
EXTENSION NUMBER
BASE NUMBER
10. THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK
TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.

11. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.

⑫ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

△ 13. A △ E SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE
WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.



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chr	-	-			product family MINITEK		rel level Released	
appr	Tim Yao	2017/07/06				MINITEK 2.0 SMT STR		rev
						cat. no. -		Product - Customer Drw
			dwg no		94626		rev E	